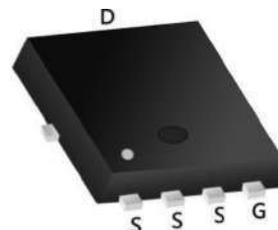


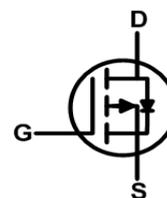
## P-Ch 30V Fast Switching MOSFETs

### Features:

- ★ Super Low Gate Charge
- ★ 100% EAS Guaranteed
- ★ Green Device Available
- ★ Excellent CdV/dt effect decline
- ★ Advanced high cell density Trench technology



PRPAK5X6 Pin Configuration



### Description:

The KPRA3031 is the high cell density trenched P-ch MOSFETs, which provide excellent RDSON and gate charge for most of the synchronous buck converter applications.

The KPRA3031 meet the RoHS and Green Product requirement, 100% EAS guaranteed with full function reliability approved.

### Product Summary

BVDSS	RDSON	ID
-30V	7.2mΩ	-70A

### Absolute Maximum Ratings

Symbol	Parameter	Rating	Units
$V_{DS}$	Drain-Source Voltage	-30	V
$V_{GS}$	Gate-Source Voltage	±20	V
$I_D@T_C=25^{\circ}C$	Continuous Drain Current, $V_{GS} @ -10V^{1,6}$	-70	A
$I_D@T_C=100^{\circ}C$	Continuous Drain Current, $V_{GS} @ -10V^{1,6}$	-50	A
$I_{DM}$	Pulsed Drain Current <sup>2</sup>	-200	A
EAS	Single Pulse Avalanche Energy <sup>3</sup>	80	mJ
$I_{AS}$	Avalanche Current	-40	A
$P_D@T_C=25^{\circ}C$	Total Power Dissipation <sup>4</sup>	90	W
$T_{STG}$	Storage Temperature Range	-55 to 175	°C
$T_J$	Operating Junction Temperature Range	-55 to 175	°C

### Thermal Data

Symbol	Parameter	Typ.	Max.	Unit
$R_{\theta JA}$	Thermal Resistance Junction-ambient <sup>1</sup> ( $t \leq 10S$ )	---	20	°C/W
	Thermal Resistance Junction-ambient <sup>1</sup> (Steady State)	---	50	°C/W
$R_{\theta JC}$	Thermal Resistance Junction-case <sup>1</sup>	---	1.6	°C/W

**Electrical Characteristics (T<sub>J</sub>=25 °C, unless otherwise noted)**

Symbol	Parameter	Conditions	Min.	Typ.	Max.	Unit
BV <sub>DSS</sub>	Drain-Source Breakdown Voltage	V <sub>GS</sub> =0V, I <sub>D</sub> =-250uA	-30	---	---	V
R <sub>DS(ON)</sub>	Static Drain-Source On-Resistance <sup>2</sup>	V <sub>GS</sub> =-10V, I <sub>D</sub> =-20A	---	6	7.2	mΩ
		V <sub>GS</sub> =-4.5V, I <sub>D</sub> =-15A	---	9.5	12	mΩ
V <sub>GS(th)</sub>	Gate Threshold Voltage	V <sub>GS</sub> =V <sub>DS</sub> , I <sub>D</sub> =-250uA	-1.2	---	-2.5	V
I <sub>DSS</sub>	Drain-Source Leakage Current	V <sub>DS</sub> =-24V, V <sub>GS</sub> =0V, T <sub>J</sub> =25°C	---	---	-1	uA
		V <sub>DS</sub> =-24V, V <sub>GS</sub> =0V, T <sub>J</sub> =55°C	---	---	-5	uA
I <sub>GSS</sub>	Gate-Source Leakage Current	V <sub>GS</sub> =±20V, V <sub>DS</sub> =0V	---	---	±100	nA
R <sub>g</sub>	Gate Resistance	V <sub>DS</sub> =0V, V <sub>GS</sub> =0V, f=1MHz	---	1.2	---	Ω
Q <sub>g</sub>	Total Gate Charge (-10V)	V <sub>DS</sub> =-15V, V <sub>GS</sub> =-10V, I <sub>D</sub> =-18A	---	60	---	nC
Q <sub>gs</sub>	Gate-Source Charge		---	9	---	
Q <sub>gd</sub>	Gate-Drain Charge		---	15	---	
T <sub>d(on)</sub>	Turn-On Delay Time	V <sub>DD</sub> =-15V, V <sub>GS</sub> =-10V, R <sub>G</sub> =3.3Ω, I <sub>D</sub> =-20A	---	17	---	ns
T <sub>r</sub>	Rise Time		---	40	---	
T <sub>d(off)</sub>	Turn-Off Delay Time		---	55	---	
T <sub>f</sub>	Fall Time		---	13	---	
C <sub>iss</sub>	Input Capacitance	V <sub>DS</sub> =-25V, V <sub>GS</sub> =0V, f=1MHz	---	3450	---	pF
C <sub>oss</sub>	Output Capacitance		---	255	---	
C <sub>rss</sub>	Reverse Transfer Capacitance		---	140	---	

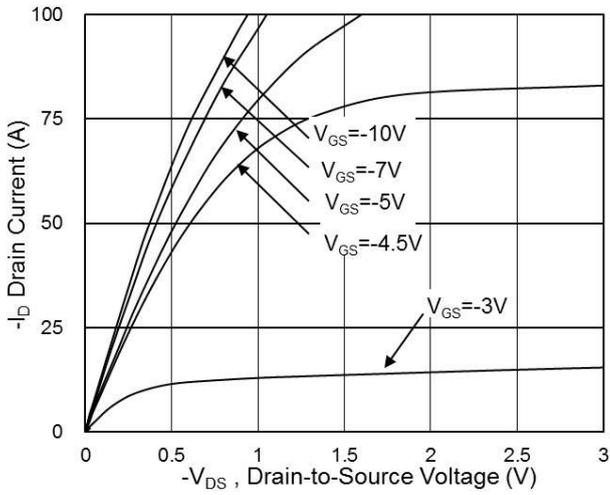
**Diode Characteristics**

Symbol	Parameter	Conditions	Min.	Typ.	Max.	Unit
I <sub>S</sub>	Continuous Source Current <sup>1,5</sup>	V <sub>G</sub> =V <sub>D</sub> =0V, Force Current	---	---	-70	A
V <sub>SD</sub>	Diode Forward Voltage <sup>2</sup>	V <sub>GS</sub> =0V, I <sub>S</sub> =-1A, T <sub>J</sub> =25°C	---	---	-1.2	V
t <sub>rr</sub>	Reverse Recovery Time	I <sub>F</sub> =-20A, di/dt=100A/μs, T <sub>J</sub> =25°C	---	22	---	nS
Q <sub>rr</sub>	Reverse Recovery Charge	T <sub>J</sub> =25°C	---	72	---	nC

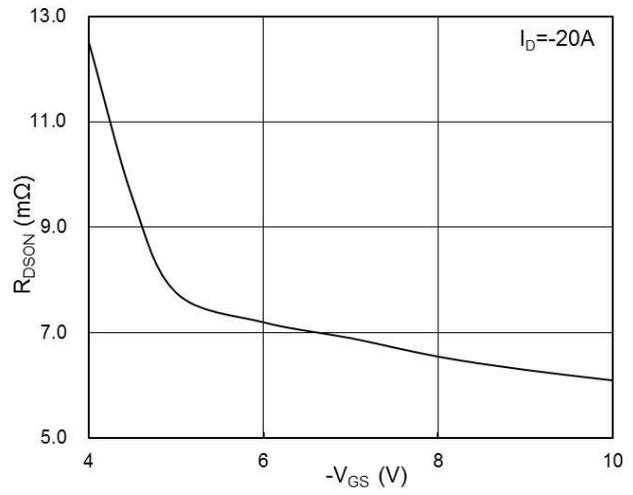
Note :

- 1.The data tested by surface mounted on a 1 inch<sup>2</sup>FR-4 board with 20Z copper.
- 2.The data tested by pulsed, pulse width ≤ 300us, duty cycle ≤ 2%
- 3.The EAS data shows Max. rating. The test condition is V<sub>DD</sub>=-50V, V<sub>GS</sub>=-10V, L=0.1mH, I<sub>AS</sub>=-40A
- 4.The power dissipation is limited by 150°C junction temperature
- 5.The data is theoretically the same as I<sub>D</sub> and I<sub>DM</sub>, in real applications, should be limited by total power dissipation
- 6.The maximum current rating is package limited.

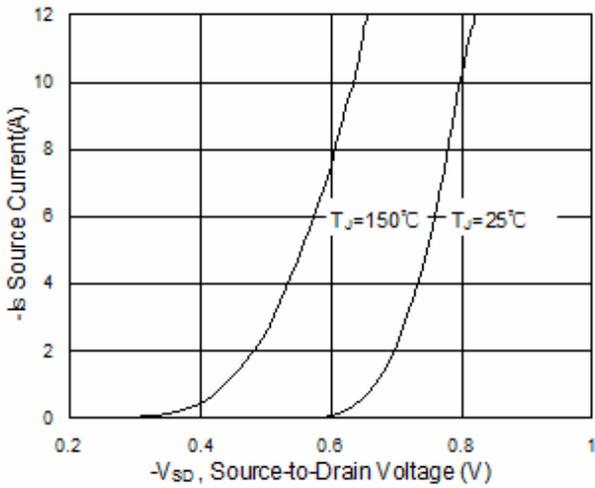
**Typical Characteristics**



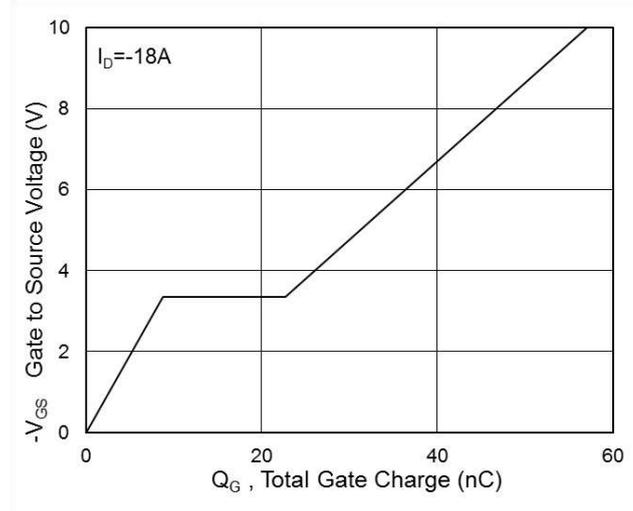
**Fig.1 Typical Output Characteristics**



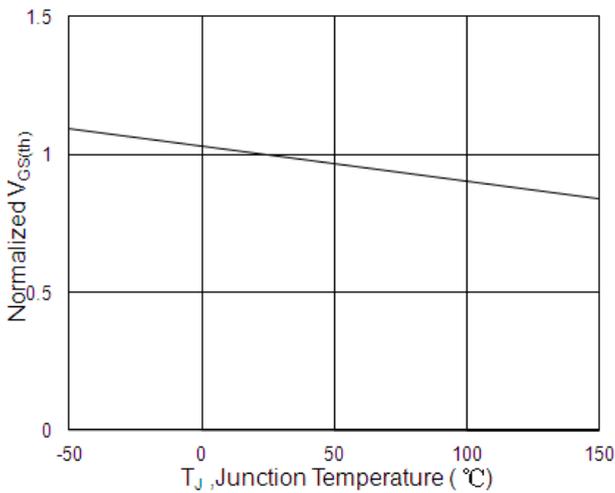
**Fig.2 On-Resistance vs G-S Voltage**



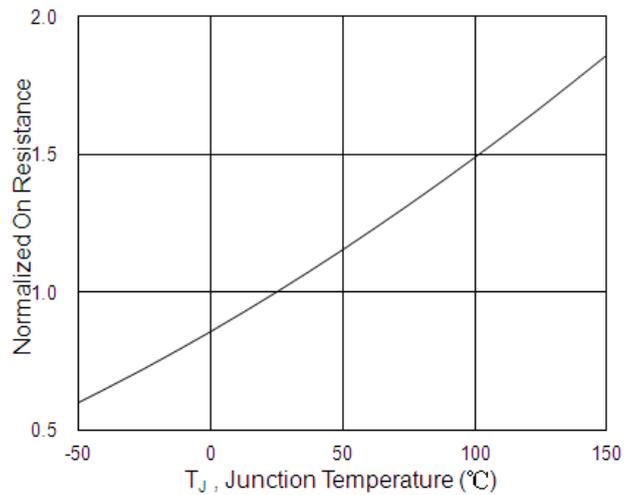
**Fig.3 Source Drain Forward Characteristics**



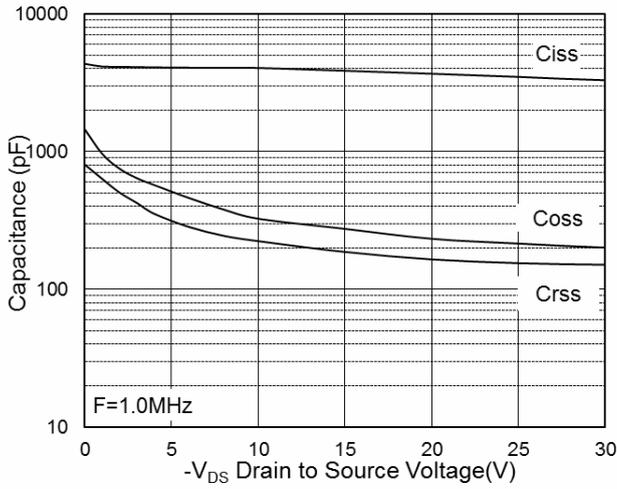
**Fig.4 Gate-Charge Characteristics**



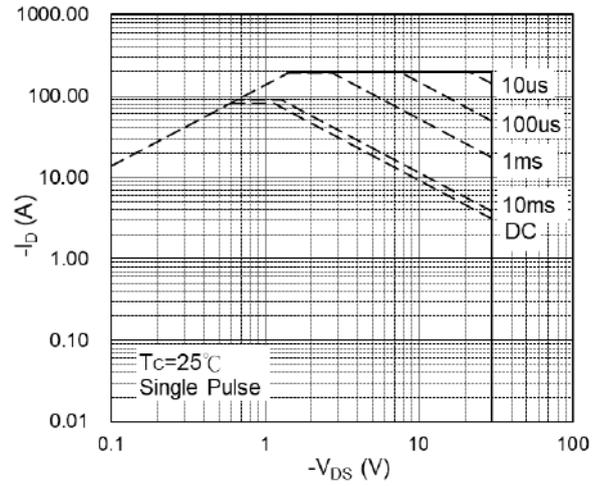
**Fig.5 Normalized  $-V_{GS(th)}$  vs  $T_J$**



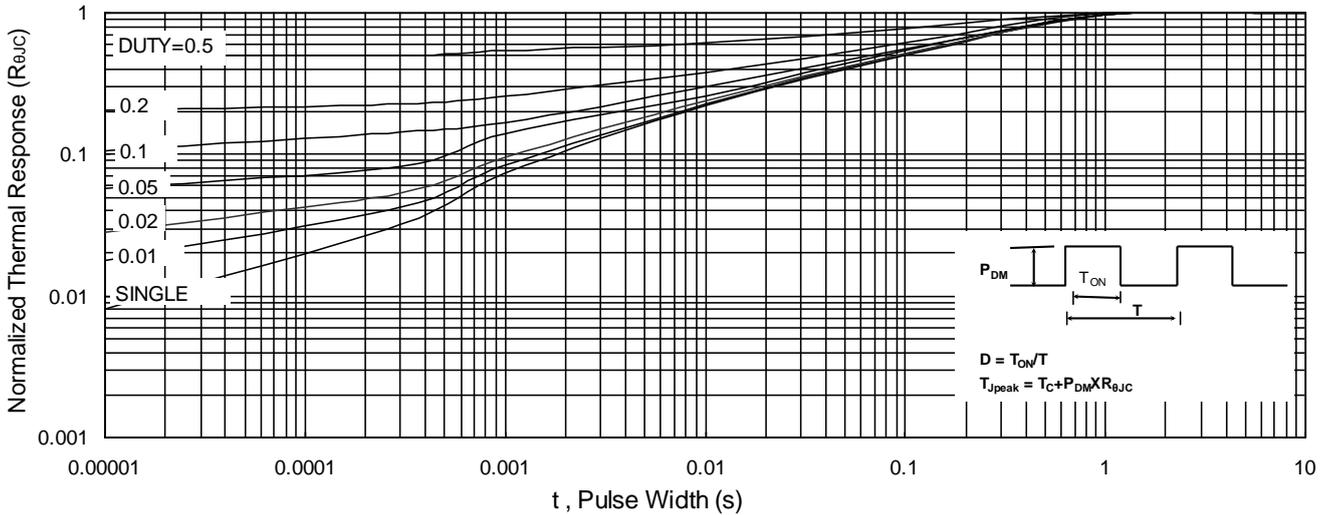
**Fig.6 Normalized  $R_{DS(on)}$  vs  $T_J$**



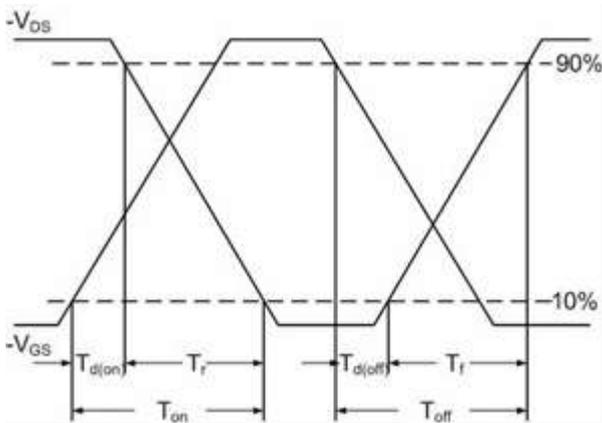
**Fig.7 Capacitance**



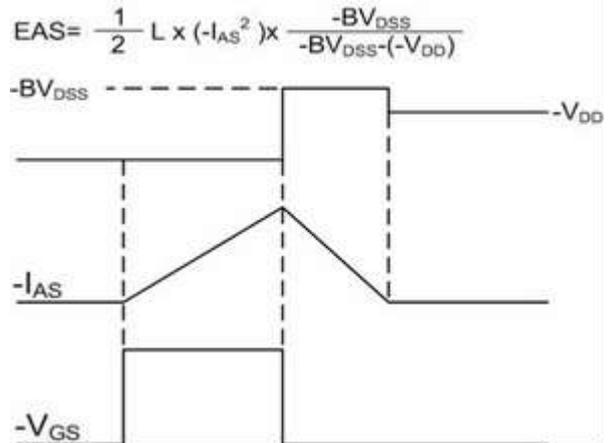
**Fig.8 Safe Operating Area**



**Fig.9 Normalized Maximum Transient Thermal Impedance**

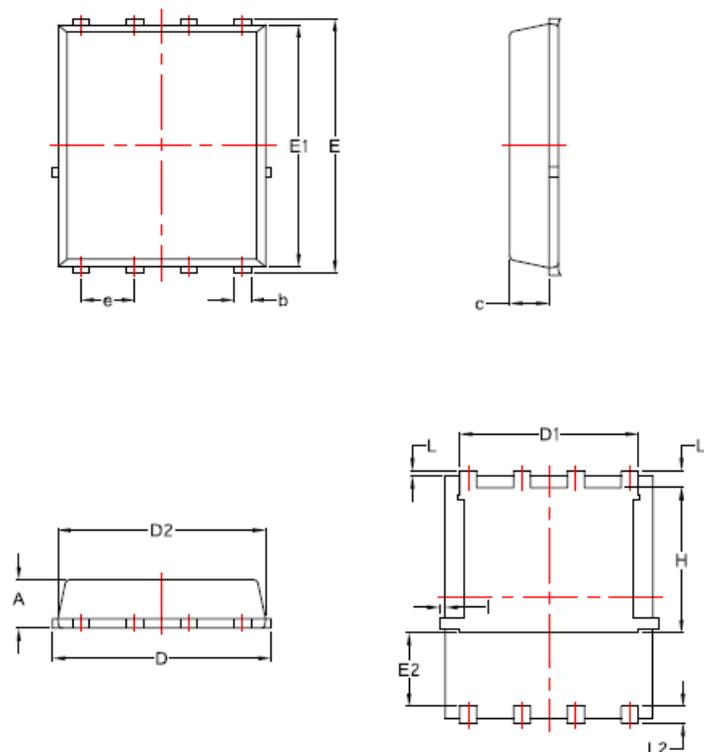


**Fig.10 Switching Time Waveform**



**Fig.11 Unclamped Inductive Switching Waveform**

## PRPAK5x6 Package Outline



SYMBOLS	MILLIMETERS		INCHES	
	MIN	MAX	MIN	MAX
A	0.90	1.20	0.0354	0.0474
b	0.30	0.51	0.0118	0.0200
c	0.60	1.046	0.0236	0.0412
D1	4.11	4.31	0.1618	0.1697
D2	4.80	5.20	0.1890	0.2047
E	5.90	6.35	0.2323	0.2500
E1	5.65	6.06	0.2224	0.2386
E2	1.10	-	0.0433	-
e	1.27 BSC		0.05 BSC	
L	0.05	0.25	0.0020	0.0098
L1	0.38	0.61	0.0150	0.0240
L2	0.30	0.71	0.0118	0.0280
H	3.30	3.92	0.1300	0.1543
I	-	0.18	-	0.0070

RECOMMENDED LAND PATTERN

